



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20230502001.1**  
**Qualify New Assembly Material set for Selected Device(s)**  
Change Notification / Sample Request

**Date:** May 08, 2023  
**To:** TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 30 days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within 30 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team ([PCN\\_admin\\_team@list.ti.com](mailto:PCN_admin_team@list.ti.com)). For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

PCN Team  
SC Business Services

**20230502001.1**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
ISO7641FCDW	null
ISO7340FCDWR	null
ISO7341CDW	null
ISO7342CDWR	null
ISO7342FCDWR	null
ISO7631FCDWR	null
ISO7640FMDW	null
ISO1050DWR	null
ISO7340CDWR	null
ISO7341CDWR	null
ISO7641FCDWR	null
AMC1305M25DWR	null
ISO7641FMDW	null
ISO7342CDW	null
AMC1304M25DW	null
AMC1204BDWR	null
ISO7330CDWR	null
ISO7331CDW	null
ISO7331FCDW	null
ISO7640FMDWR	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20230502001.1		<b>PCN Date:</b>	May 08, 2023	
<b>Title:</b>	Qualify New Assembly Material set for Selected Device(s)				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services		
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Aug 08, 2023	<b>Sample requests accepted until:</b>	June 08, 2023*		
<b>*Sample requests received after June 08, 2023 will not be supported.</b>					
<b>Change Type:</b>					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
				<input type="checkbox"/>	Wafer Fab Process
<b>PCN Details</b>					
<b>Description of Change:</b>					
<p>Texas Instruments is pleased to announce the qualification of new assembly material for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:</p>					
<b>Group 1 Device:</b>					
	<b>Material</b>	<b>Current</b>	<b>Proposed</b>		
	Wire type	0.96mil Au	0.8mil Cu		
<b>Group 2 Device:</b>					
	<b>Material</b>	<b>Current</b>	<b>Proposed</b>		
	Wire type	0.96mil Au	0.8mil Cu		
	Mold compound	4209640	4221499		
<b>Group 3 Device:</b>					
	<b>Material</b>	<b>Current</b>	<b>Proposed</b>		
	Wire type	0.96mil Au	0.8mil Cu		
	Mount compound	4042500	4211470		
	Mold compound	4209640	4221499		
<b>Reason for Change:</b>					
<p>Continuity of supply.</p> <ol style="list-style-type: none"> <li>1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties</li> <li>2) Maximize flexibility within our Assembly/Test production sites.</li> <li>3) Cu is easier to obtain and stock</li> </ol>					
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>					
None					
<b>Impact on Environmental Ratings</b>					
<p>Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.</p>					
	<b>RoHS</b>	<b>REACH</b>	<b>Green Status</b>	<b>IEC 62474</b>	
	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	

**Changes to product identification resulting from this PCN:**

None

**Product Affected:**

**Group 1:**

AMC1204BDW	AMC1304L25DW	AMC1305F25DW	AMC1305M25DW
AMC1204BDWR	AMC1304L25DWR	AMC1305F25DWR	AMC1305M25DWR
AMC1204DW	AMC1304M05DW	AMC1305L25DW	AMC1307M05DWR
AMC1204DWR	AMC1304M05DWR	AMC1305L25DWR	
AMC1304L05DW	AMC1304M25DW	AMC1305M05DW	
AMC1304L05DWR	AMC1304M25DWR	AMC1305M05DWR	

**Group 2:**

ISO1050DW	ISO7331CDWR	ISO7341CDW	ISO7342FCDWR
ISO1050DWR	ISO7331FCDW	ISO7341CDWR	ISO7520CDW
ISO7330CDW	ISO7331FCDWR	ISO7341FCDW	ISO7520CDWR
ISO7330CDWR	ISO7340CDW	ISO7341FCDWR	ISO7521CDW
ISO7330FCDW	ISO7340CDWR	ISO7342CDW	ISO7521CDWR
ISO7330FCDWR	ISO7340FCDW	ISO7342CDWR	SN1007074DW
ISO7331CDW	ISO7340FCDWR	ISO7342FCDW	SN1007074DWR

**Group 3:**

ISO7631FCDW	ISO7631FMDWR	ISO7641FCDW	ISO7641FMDWR
ISO7631FCDWR	ISO7640FMDW	ISO7641FCDWR	
ISO7631FMDW	ISO7640FMDWR	ISO7641FMDW	

## Qualification Report

Automotive New Product Qualification Summary  
(As per AEC-Q100 and JEDEC Guidelines)  
Approve Date 28-Apr-2023

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: AMC1305M25QDW01	Qual Device: AMC1305M25QDW01	QBS Reference: AMC1305M25QDWR01	QBS Reference: AMC1305M25QDWR01
<b>Test Group A - Accelerated Environment Stress Tests</b>											
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	1 Step	No Fails	No Fails	No Fails	No Fails
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	1/5/0	1/5/0	1/5/0	1/5/0

HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	3/135/0	3/135/0	1/45/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	-	-	1/45/0
<b>Test Group B - Accelerated Lifetime Simulation Tests</b>											
HTOL	B1	JEDEC JESD22-A108	1	77	Life Test	150C	408 Hours	-	-	1/77/0	3/231/0
ELFR	B2	AEC Q100-008	1	77	Early Life Failure Rate	150C	24 Hours	-	-	-	3/2400/0
<b>Test Group C - Package Assembly Integrity Tests</b>											
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0	3/90/0
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-	1/15/0	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	1/15/0	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	1	10	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	3/30/0
<b>Test Group D - Die Fabrication Reliability Tests</b>											
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
NBTI	D4	-	-	-	Negative Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
<b>Test Group E - Electrical Verification Tests</b>											
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	-	-	1/3/0	1/3/0
LU	E4	AEC Q100-004	1	6	Latch-Up	Per AEC Q100-004	-	-	-	1/6/0	1/6/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	3/90/0	3/90/0	3/90/0	3/90/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1 k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

**Ambient Operating Temperature by Automotive Grade Level:**

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

**E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):**

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW PCN Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>

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